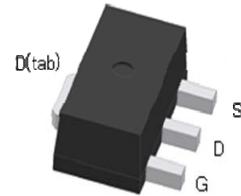
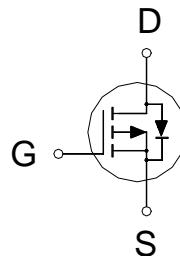


P-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	-60V
R _{DSON} (MAX.)	150mΩ
I _D	-2.4A



Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNIT
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	-2.4	A
		-1.5	
Pulsed Drain Current ¹	I _{DM}	-9.6	
Power Dissipation	P _D	1.47	W
		0.94	
Operating Junction & Storage Temperature Range	T _j , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R _{θJC}	18	85	°C / W
Junction-to-Ambient ³	R _{θJA}			

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

³85°C / W when mounted on a 1 in² pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

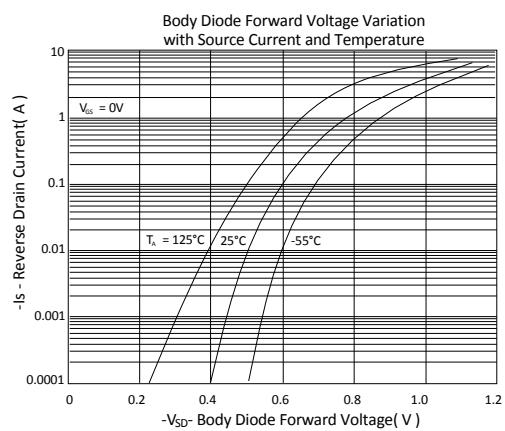
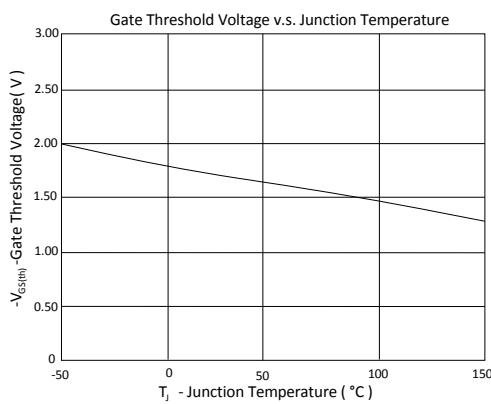
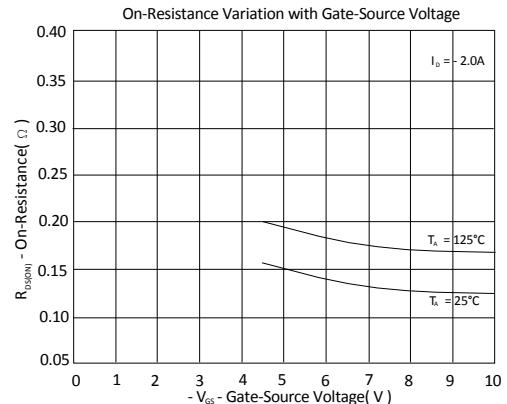
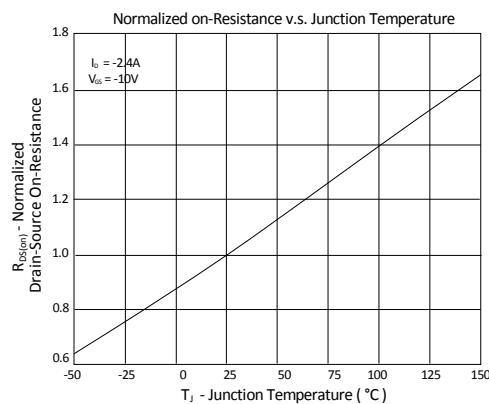
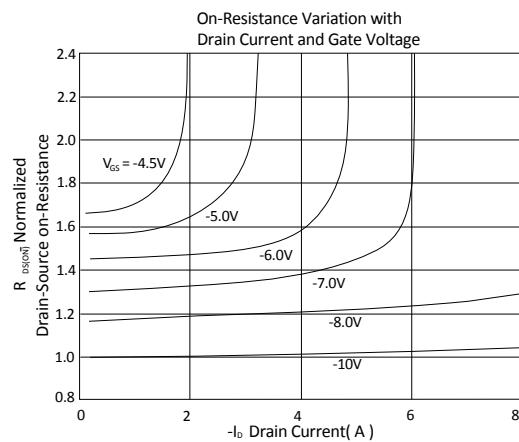
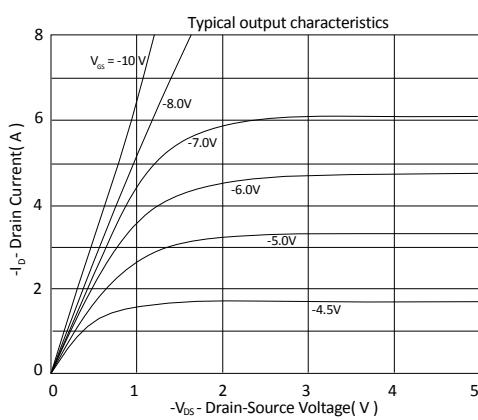
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-60			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-1.7	-3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -48V, V_{GS} = 0V$			-1	μA
		$V_{DS} = -40V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			-25	
On-State Drain Current ¹	$I_{D(\text{ON})}$	$V_{DS} = -5V, V_{GS} = -10V$	-2.4			A
Drain-Source On-State Resistance ¹	$R_{DS(\text{ON})}$	$V_{GS} = -10V, I_D = -2.4\text{A}$		125	150	$\text{m}\Omega$
		$V_{GS} = -4.5V, I_D = -2.0\text{A}$		160	200	
Forward Transconductance ¹	g_{fs}	$V_{DS} = -5V, I_D = -2\text{A}$		3		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -30V, f = 1\text{MHz}$		1032		pF
Output Capacitance	C_{oss}			66		
Reverse Transfer Capacitance	C_{rss}			48		
Total Gate Charge ^{1,2}	Q_g	$V_{DS} = -10V, V_{GS} = -10V, I_D = -2\text{A}$		12.3		nC
Gate-Source Charge ^{1,2}	Q_{gs}			1.6		
Gate-Drain Charge ^{1,2}	Q_{gd}			2.4		
Turn-On Delay Time ^{1,2}	$t_{d(\text{on})}$	$V_{DS} = -10V, I_D = -1\text{A}, V_{GS} = -10V, R_{GS} = 6\Omega$		12		nS
Rise Time ^{1,2}	t_r			20		
Turn-Off Delay Time ^{1,2}	$t_{d(\text{off})}$			20		
Fall Time ^{1,2}	t_f			25		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_C = 25^\circ\text{C}$)						
Continuous Current	I_S				-2.4	A
Pulsed Current ³	I_{SM}				-9.6	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{GS} = 0V$			1.2	V

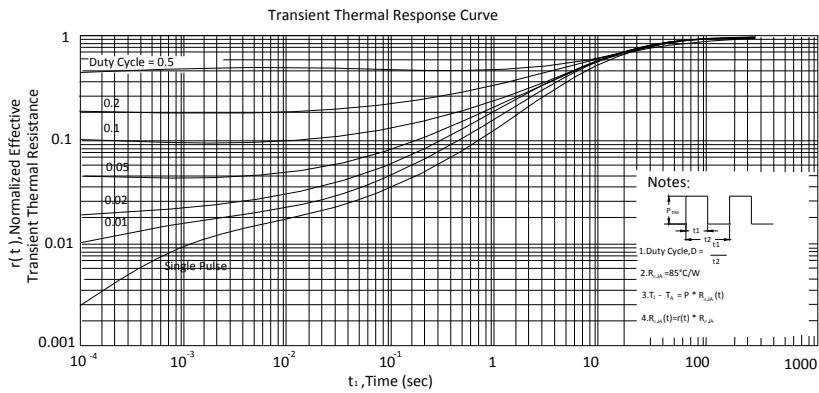
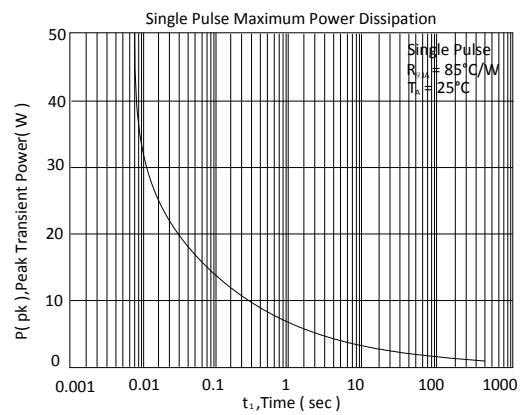
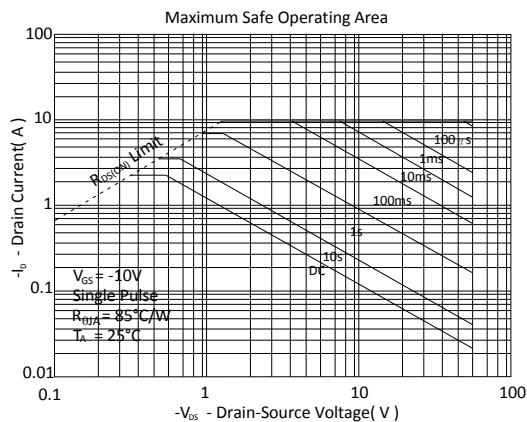
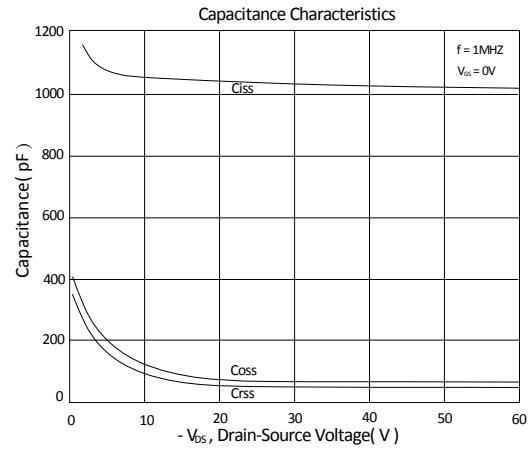
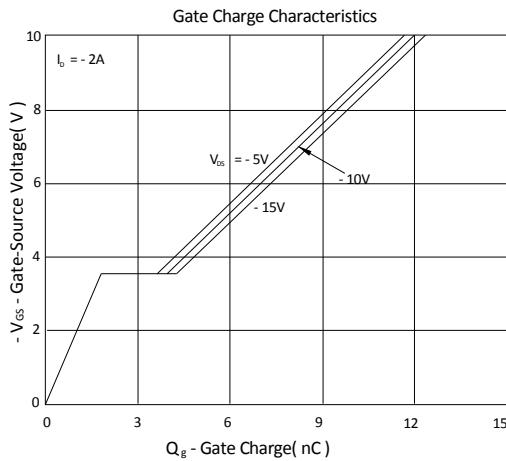
¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

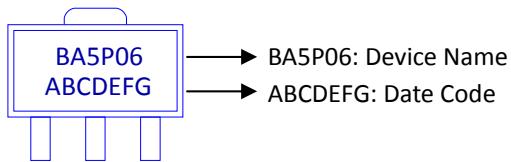
TYPICAL CHARACTERISTICS



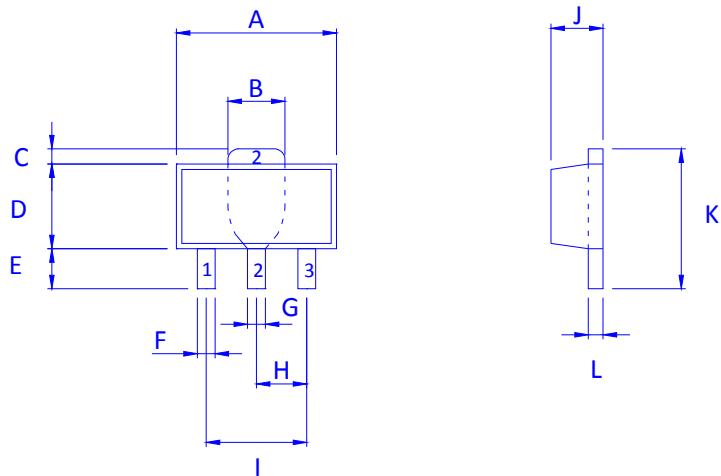


Ordering & Marking Information:

Device Name: EMBA5P06P for SOT-89



Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K	L
in.	4.30	1.60	0.40	2.40	0.80	0.40	0.40	1.40	2.80	1.30	3.80	0.30
Typ.												
Max.	4.70	1.80	0.60	2.60	1.40	0.50	0.60	1.60	3.20	1.70	4.60	0.50

Footprint

